

L Number	Hits	Search Text	DB	Time stamp
10	293	(Conductive adj (adhesive ink paste) interface adj material polymer adj solder) and (indium silver copper aluminum tin bismuth gallium In Ag Cu Al Sn Bi Ga) same ( powder granule flake) and (vinyl adj "q" adj resin tetravinyl adj tetramethyl adj cyclotetrasiloxane vinyl adj silicone hydride near2 siloxane siloxane )	USPAT; US-PGPUB	2004/10/29 13:02
11	185	((Conductive adj (adhesive ink paste) interface adj material polymer adj solder) and (indium silver copper aluminum tin bismuth gallium In Ag Cu Al Sn Bi Ga) same ( powder granule flake) and (vinyl adj "q" adj resin tetravinyl adj tetramethyl adj cyclotetrasiloxane vinyl adj silicone hydride near2 siloxane siloxane ) ) and (wt weight ) near2 ('%' percent)	USPAT; US-PGPUB	2004/10/29 13:02
12	41	((((Conductive adj (adhesive ink paste) interface adj material polymer adj solder) and (indium silver copper aluminum tin bismuth gallium In Ag Cu Al Sn Bi Ga) same ( powder granule flake) and (vinyl adj "q" adj resin tetravinyl adj tetramethyl adj cyclotetrasiloxane vinyl adj silicone hydride near2 siloxane siloxane ) ) and (wt weight ) near2 ('%' percent))) and (graphite carbon) near2 (fibril nanotube fiber microfiber)	USPAT; US-PGPUB	2004/10/29 13:02
13	2	((Conductive adj (adhesive ink paste) interface adj material polymer adj solder) and (indium silver copper aluminum tin bismuth gallium In Ag Cu Al Sn Bi Ga) same ( powder granule flake) and (vinyl adj "q" adj resin tetravinyl adj tetramethyl adj cyclotetrasiloxane vinyl adj silicone hydride near2 siloxane siloxane ) ) and ('InSn' 'InAg' 'SnAgCu' 'SnBi')	USPAT; US-PGPUB	2004/10/29 13:02
14	60	((((conductive thermal\$3) near5 (paste ink)) Interface adj material polymer adj solder) and (indium silver copper aluminum tin bismuth gallium In Ag Cu Al Sn Bi Ga) near5 ( powder flake) and ( silicone siloxane)	EPO; JPO; DERWENT	2004/10/29 13:02
15	60	nguyen near2 my.in.	USPAT; US-PGPUB	2004/10/29 13:03